IEEE
IEEE Reliability/CPMT/ED Singapore Chapter

First Call For Registration

CPMT
IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

EPTC 2007 Conference: 10th – 12th December 2007, Singapore

EPTC 2007 will feature 35 technical sessions with nearly 200 paper presentations by researchers from 19 countries; 7 invited papers by technical leaders in various categories; 6 short courses to be conducted by international experts and exhibition with participation of over 20 companies. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation to reliability. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

KEYNOTE ADDRESSES - 11TH DEC 2007

"Package Trends for Mobile & Communication Platforms" - Dr. Ralf Pleninger*, Senior Director, Infineon Technologies, Germany*

"Trends of Technologies for Heterogeneous Integration" - Prof. Herbert Reichl*, Director, Fraunhofer Institute of Micro integration & Reliability, IZM, Germany*

LUNCHEON TALKS - 11TH & 12TH DEC 2007

"Global Packaging Challenges" - Prof Rao Tummala*, Founding Director, Packaging Research Center, Georgia Institute of Technology, USA*

"Market and Technological Trends in Silicon IC and its Impact on Packaging Assembly" - Dr Sanjay Singh*, Director - Industrial Technologies, Frost & Sullivan Asia Pacific.*

INVITED PAPERS:

- **Package-On-Package Mechanical Reliability Characterization - *Masazumi Amagai***, *Texas Instruments, Japan*
- **Advances in Embedded Chip Packaging - *Charles Bauer***, *Tech Lead, USA*
- **Lasers for Packaging Applications - *Nick Konidaris***, *Electro Scientific Industries, USA*
- **Interfacial Reliability of SnAgCu Solder Joints - *Kejun Zeng***, *Texas Instruments, USA*
- **Testing Interface Thermal Resistance - *Marta Rencz***, *MicReD, Hungary*
- **Building Accuracies in Finite Element Models for Life Prediction of Solder Joints** - ***Ahmer Syed***, *Amkor, USA*
- **Electromigration and Sn Whisker Growth in Flip Chip Pb-Free Solder Joints** - ***King Ning Tu***, *UCLA, USA*

SHORT COURSES – 10 DEC 2007

Morning Session	Afternoon Session
Emerging Trend to SOP after SIP and 3D Packaging **Prof. Rao Tummala,** *Georgia Tech, USA*	**Signal Integrity and Embedded Passives** **A/Prof. Joungho Kim,** *KAIST, Korea* **Dr. Albert Lu,** *SIMTech, Singapore*
Design For Reliability and Reliability Testing & Statistical Analysis of Lead-Free Solder Joints **Dr. John Lau,** *IME, Singapore*	**Electromigration in Interconnect and Packaging Technologies** **Prof. King Ning Tu,** *UCLA, USA*
Analysis of Delamination in IC Packages Using the Fracture Mechanics Approach **Prof. Andrew Tay,** *NUS, Singapore*	**Dynamic Response of Micro- and Opto- Electronic Systems to Shocks and Vibrations** **Prof. Ephraim Suhir,** *UC Santa Cruz, USA*

More & More - it for - More Than Moore
Technology Exhibits, Poster Presentations, Industry Networking,
Parallel Technical Sessions & Industry Panel Discussion

EPTC 2007 REGISTRATION

http://www.eptc-ieee.net/registration/ Email: **secretariat@eptc-ieee.net / ivan@inmeet.com.sg**

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